

## **ABSTRACT**

A method is taught for applying and accurately locating a plurality of caps to a plurality of microfabricated devices at the wafer stage. The method involves using a two part mold to make a plurality of first hollow molded caps. The caps are made from a layer of thermoplastic material which is placed in the mold. Each cap having a central portion and a perimeter wall. The mold is opened so that the caps are carried by the first half. The caps are applied to a wafer using the first half. After the caps are applied, the wafer may be separated into individual chips.